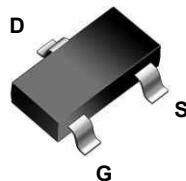
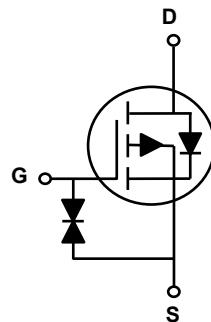


Main Product Characteristics

V_{DSS}	-20V
$R_{DS(ON)}$	600mΩ (typ.)
I_D	-450mA



SOT-523



Schematic Diagram

Features and Benefits

- Advanced trench MOSFET process technology
- Special designed for battery protection, load switching and general power management
- Ultra low on-resistance with low gate charge
- Fast switching and reverse body recovery
- 150°C operating temperature
- ESD protection up to 2KV



Description

The SSF2319CJ1 utilizes the latest techniques to achieve high cell density and low on-resistance. These features make this device extremely efficient and reliable for use in high efficiency switch mode power supplies and a wide variety of other applications.

Absolute Maximum Ratings ($T_A=25^\circ\text{C}$ unless otherwise specified)

Parameter	Symbol	Max.	Unit
Drain-Source Voltage	V_{DS}	-20	V
Gate-Source Voltage	V_{GS}	± 8	V
Drain Current-Continuous ($T_C=25^\circ\text{C}$)	I_D	-450	mA
Drain Current-Continuous ($T_C=100^\circ\text{C}$)		-280	
Drain Current-Pulsed ¹	I_{DM}	-1.7	A
Power Dissipation	P_D	312	mW
Thermal Resistance, Junction-to-Ambient ²	$R_{\theta JA}$	450	°C/W
Operating Junction Temperature Range	T_J	-55 To +150	°C
Storage Temperature Range	T_{STG}	-55 To +150	°C

Electrical Characteristics ($T_A=25^\circ\text{C}$ unless otherwise specified)

Parameter	Symbol	Conditions	Min.	Typ.	Max.	Unit
On / Off Characteristics						
Drain-Source Breakdown Voltage	BV_{DSS}	$V_{\text{GS}}=0\text{V}, I_{\text{D}}=-250\mu\text{A}$	-20	-	-	V
BV_{DSS} Temperature Coefficient	$\Delta \text{BV}_{\text{DSS}} / \Delta T_J$	Reference to 25°C , $I_{\text{D}}=-1\text{mA}$	-	-0.01	-	V°C
Drain-Source Leakage Current	$I_{\text{DS}}^{\text{SS}}$	$V_{\text{DS}}=-20\text{V}, V_{\text{GS}}=0\text{V}$	-	-	-1	μA
Gate-Source Leakage Current	$I_{\text{GS}}^{\text{SS}}$	$V_{\text{GS}}=\pm 6\text{V}, V_{\text{DS}}=0\text{V}$	-	-	± 20	μA
		$V_{\text{GS}}=\pm 4.5\text{V}, V_{\text{DS}}=0\text{V}$	-	-	± 2	μA
Static Drain-Source On-Resistance ³	$R_{\text{DS(ON)}}$	$V_{\text{GS}}=-4.5\text{V}, I_{\text{D}}=-0.3\text{A}$	-	440	600	$\text{m}\Omega$
		$V_{\text{GS}}=-2.5\text{V}, I_{\text{D}}=-0.2\text{A}$		610	850	
		$V_{\text{GS}}=-1.8\text{V}, I_{\text{D}}=-0.1\text{A}$		810	1200	
		$V_{\text{GS}}=-1.5\text{V}, I_{\text{D}}=-0.1\text{A}$		1020	1600	
		$V_{\text{GS}}=-1.2\text{V}, I_{\text{D}}=-0.1\text{A}$	-	1800	3000	
Gate Threshold Voltage ³	$V_{\text{GS(th)}}$	$V_{\text{GS}}=V_{\text{DS}}, I_{\text{D}}=-250\mu\text{A}$	-0.3	-0.6	-1	V
$V_{\text{GS(th)}}$ Temperature Coefficient ³	$\Delta V_{\text{GS(th)}}$		-	3	-	mV°C
Dynamic and Switching Characteristics						
Total Gate Charge ⁴	Q_g	$V_{\text{DS}}=-10\text{V}, I_{\text{D}}=-0.2\text{A}$ $V_{\text{GS}}=-4.5\text{V}$	-	1	2	nC
Gate-Source Charge ⁴	Q_{gs}		-	0.28	0.5	
Gate-Drain Charge ⁴	Q_{gd}		-	0.18	0.4	
Turn-On Delay Time ⁴	$t_{\text{d(on)}}$	$V_{\text{DD}}=-10\text{V}, R_{\text{G}}=10\Omega$ $V_{\text{GS}}=-4.5\text{V}, I_{\text{D}}=0.2\text{A}$	-	8	16	nS
Rise Time ⁴	t_r		-	5.2	10	
Turn-Off Delay Time ⁴	$t_{\text{d(off)}}$		-	30	60	
Fall Time ⁴	t_f		-	18	36	
Input Capacitance ⁴	C_{iss}	$V_{\text{DS}}=-10\text{V}, V_{\text{GS}}=0\text{V}, F=1\text{MHz}$	-	40	78	pF
Output Capacitance ⁴	C_{oss}		-	15	30	
Reverse Transfer Capacitance ⁴	C_{rss}		-	6.5	13	
Drain-Source Diode Characteristics and Maximum Ratings						
Diode Forward Current ²	I_s	$V_G=V_D=0\text{V}$, Force Current	-	-	-400	mA
Diode Forward Voltage ³	V_{SD}	$V_{\text{GS}}=0\text{V}, I_s=-0.2\text{A}$	-	-0.8	-1	V

Note:

1. Repetitive rating: Pulsed width limited by maximum junction temperature.
2. Surface Mounted on FR4 Board, $t \leq 10\text{sec}$.
3. Pulse test: pulse width $\leq 300\text{us}$, duty cycle $\leq 2\%$.
4. Guaranteed by design, not subject to production testing.

Typical Electrical and Thermal Characteristics

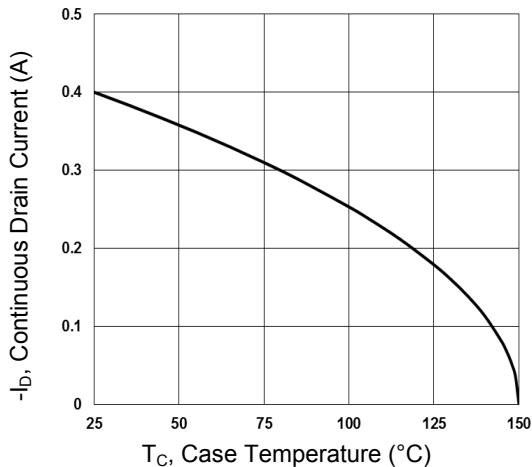


Figure 1. Drain Current vs. T_c

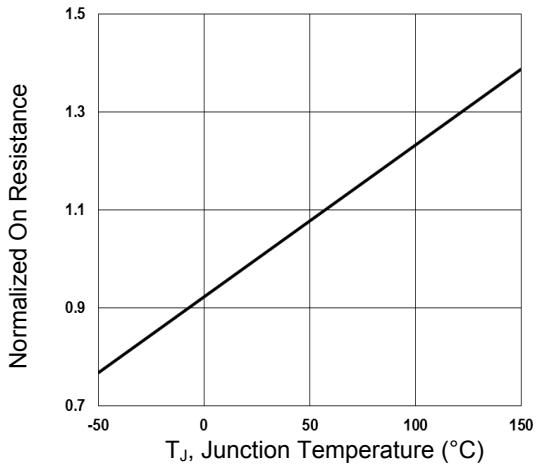


Figure 2. Normalized R_{DS(on)} vs. T_j

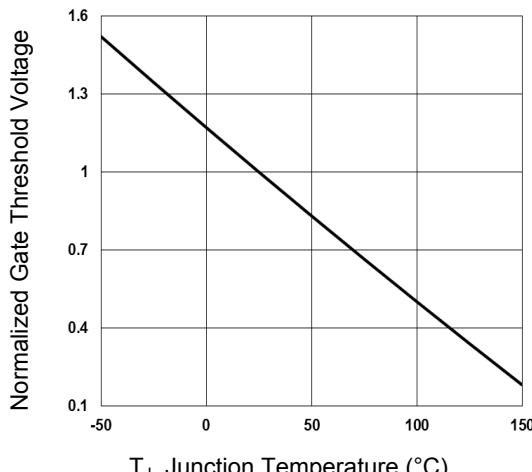


Figure 3. Normalized V_{th} vs. T_j

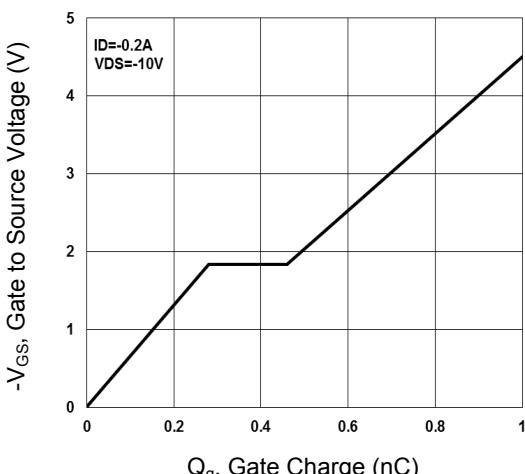


Figure 4. Gate Charge Waveform

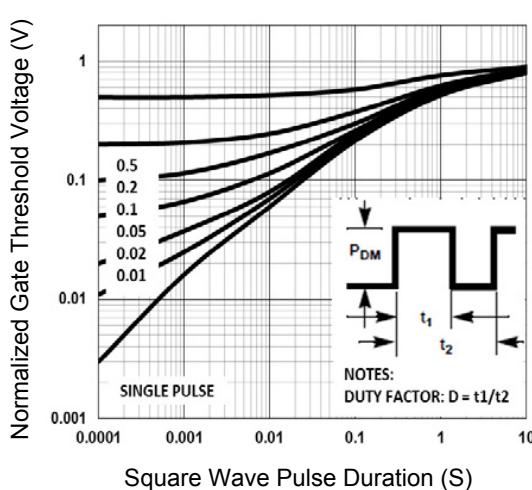


Figure 5. Normalized Transient Response

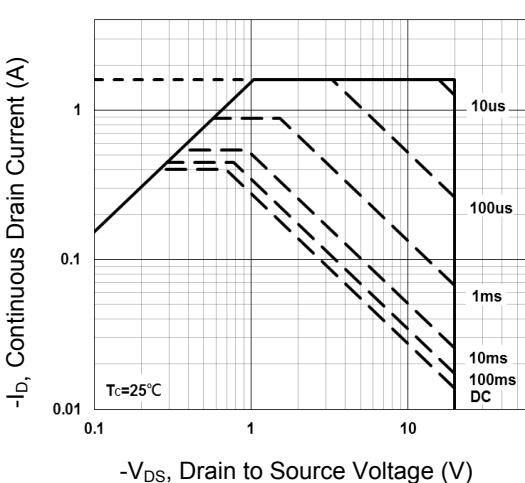
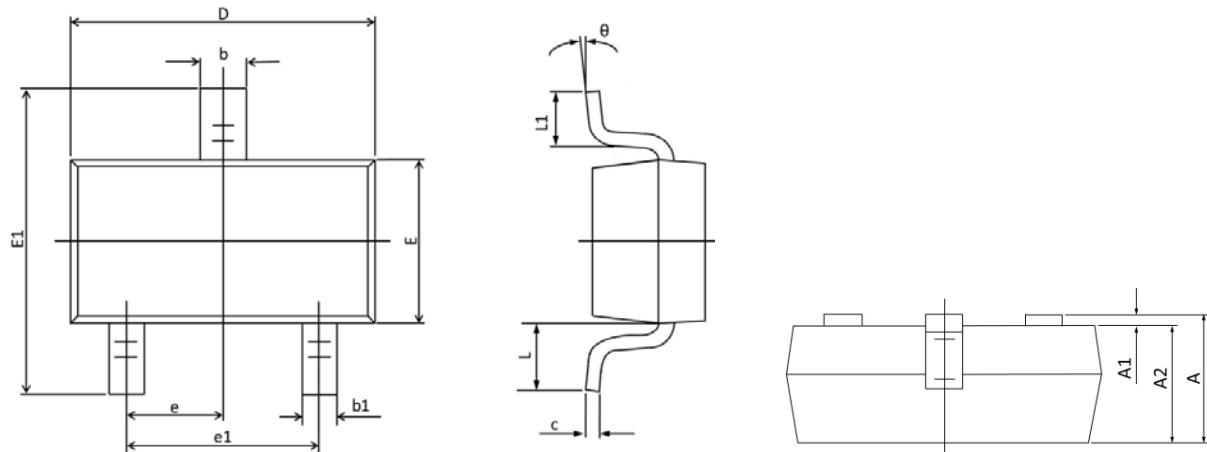


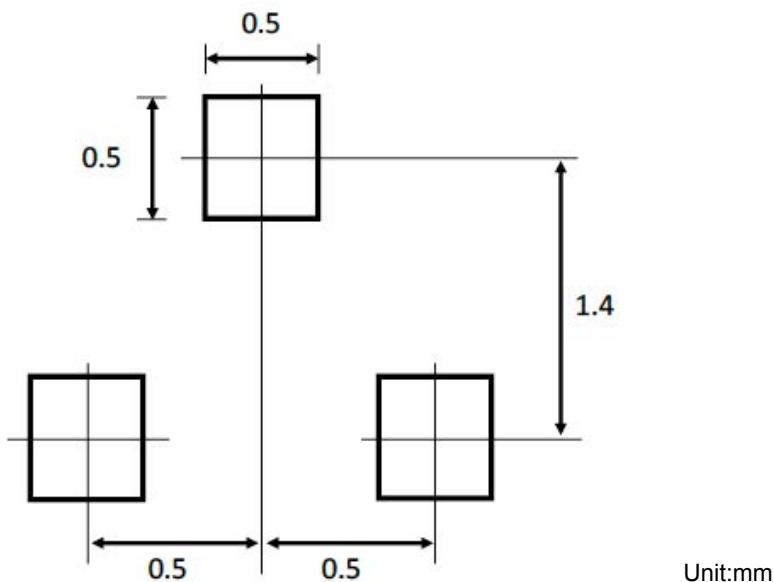
Figure 6. Safe Operation Area

Package Outline Dimensions (SOT-523)



Symbol	Dimensions in Millimeters		Dimensions in Inches	
	Min	Max	Min	Max
A	0.700	0.900	0.028	0.035
A1	0.000	0.100	0.000	0.004
A2	0.700	0.800	0.028	0.031
b	0.250	0.350	0.010	0.014
b1	0.150	0.250	0.006	0.010
c	0.100	0.200	0.004	0.008
D	1.500	1.750	0.059	0.069
E	0.700	0.900	0.028	0.035
E1	1.400	1.750	0.055	0.069
e	0.500 TYP		0.020 TYP	
e1	0.900	1.100	0.035	0.043
L	0.300	0.460	0.012	0.018
L1	0.260	0.460	0.010	0.018
θ	0°	8°	0°	8°

Recommended Pad Layout



Order Information

Device	Package	Marking	Carrier	Quantity
SSF2319CJ1	SOT-523	F	Tape & Reel	3,000 pcs / Reel